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- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) 2-µ Process
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  < 0.8 V at V<sub>CC</sub>, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  2 V at V<sub>CC</sub>, T<sub>A</sub> = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs

#### description

These octal transparent D-type latches are designed for 2.7-V to 5.5-V V<sub>CC</sub> operation.

While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (OE) input can be used to place the eight outputs in either a normal logic

state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

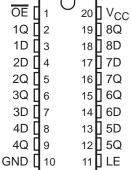
OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN74LV373 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

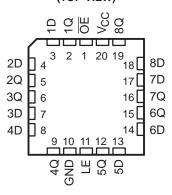
The SN54LV373 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LV373 is characterized for operation from –40°C to 85°C.

# SN74LV373 . . . DB, DW, OR PW PACKAGE (TOP VIEW)

SN54LV373 . . . J OR W PACKAGE



### SN54LV373 . . . FK PACKAGE (TOP VIEW)



### FUNCTION TABLE (each latch)

	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	$Q_0$
Н	X	Χ	Z



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TEXAS INSTRUMENTS

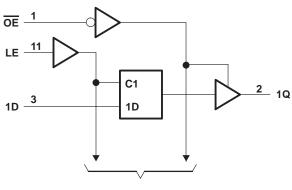
### SN54LV373, SN74LV373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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#### logic symbol†

#### OE ΕN 11 LE C1 2 3 1D 1Q 5 4 2Q 2D 6 7 3D 3Q 9 8 4Q 4D 13 12 5Q 5D 14 15 6D 6Q 17 16 7D 7Q 18 19 8D

#### logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for DB, DW, J, PW, and W packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	$-0.5\;V$ to 7 $V$
Input voltage range, V <sub>I</sub> (see Note 1)	$V$ to $V_{CC}$ + 0.5 $V$
Output voltage range, V <sub>O</sub> (see Notes 1 and 2)	V to $V_{CC}$ + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±35 mA
Continuous current through V <sub>CC</sub> or GND	$\dots \dots  \pm 70 \; mA$
Maximum power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 3): DB package	0.6 W
DW package	1.6 W
PW package	0.7 W
Storage temperature range, T <sub>stg</sub>	−65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. This value is limited to 7 V maximum.
  - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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#### recommended operating conditions (see Note 4)

			SN54L	.V373	SN74L	.V373	LINUT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2.7	5.5	2.7	5.5	V
	I link to set input sette en	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		2		V
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	3.15		3.15		V
.,	Law Israel Sancturella na	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		8.0	.,
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		1.65		1.65	V
٧ <sub>I</sub>	Input voltage		0	VCC	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	V
	I Pale I and and an and	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	20	-8		-8	4
ЮН	High-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	140	-16		-16	mA
		V <sub>CC</sub> = 2.7 V to 3.6 V	V	8		8	
lOL	Low-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		16		16	mA
Δt/Δν	Input transition rise or fall rate		0	100	0	100	ns/V
T <sub>A</sub>	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TT-07-00-10-10-10-10-10-10-10-10-10-10-10-10-		SN	154LV37	3	SN	174LV37	3		
PARAMETER	TEST CONDITIONS	v <sub>cc</sub> †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
Voн	I <sub>OH</sub> = -100 μA	MIN to MAX	V <sub>CC</sub> -0.	.2		V <sub>CC</sub> -0.	.2			
	$I_{OH} = -8 \text{ mA}$	3 V	2.4			2.4			V	
	$I_{OH} = -16 \text{ mA}$	4.5 V	3.6			3.6				
	I <sub>OL</sub> = 100 μA	MIN to MAX			0.2			0.2		
$V_{OL}$	I <sub>OL</sub> = 8 mA	3 V			0.4			0.4	V	
-	I <sub>OL</sub> = 16 mA	4.5 V			0.55			0.55		
IĮ	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V		Ź	±1			±1		
		5.5 V		ZE I	±1			±1	μΑ	
	$V_O = V_{CC}$ or GND	3.6 V		2	±5			±5		
I <sub>OZ</sub>		5.5 V		Ç,	±5			±5	μΑ	
	V V 0ND 1 0	3.6 V	5	)	20			20		
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	Q <sup>+</sup>		20			20	μΑ	
ΔICC	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V			500			500	μА	
		3.3 V		2.5			2.5			
Ci	$V_I = V_{CC}$ or GND	5 V		3			3		pF	
_		3.3 V		7			7		pF	
Co	$V_O = V_{CC}$ or GND	5 V		7.5			7.5			

<sup>&</sup>lt;sup>†</sup> For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

### SN54LV373, SN74LV373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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## timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

					SN54LV3	73		
			V <sub>CC</sub> = 5	$V \pm 0.5 V$	V <sub>CC</sub> = 3.3	V ± 0.3 V	V <sub>CC</sub> = 2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN MAX	
t <sub>W</sub>	Pulse duration, LE high		10		010 1	_	178	ns
t <sub>su</sub>	Setup time, data before LE $\downarrow$	High or low	4	<	P.O. Elli	pRo	6	ns
th	Hold time, data after LE↓	High or low	6		6	<	6	ns

### timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

					SN74LV	373			
			V <sub>CC</sub> = 5	$V \pm 0.5 V$	V <sub>CC</sub> = 3.3	$3~V\pm0.3~V$	VCC =	= 2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>W</sub>	Pulse duration, LE high		10		10		8		ns
t <sub>su</sub>	Setup time, data before LE $\downarrow$	High or low	4		6		6		ns
th	Hold time, data after LE↓	High or low	6		6	·	6		ns

### switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)	SN54LV373												
PARAMETER	FROM (INPUT)		_	-	(OUTPUT)	-	_	VCC:	= 5 V ± (	).5 V	VCC =	3.3 V ±	0.3 V	VCC =	2.7 V
	( 01)	(0011 01)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX					
,	D	_		8	16	<u></u>	11	22	<u></u>	28					
<sup>t</sup> pd	LE	Q		11	19	W.	15	25	LIN .	26	ns				
t <sub>en</sub>	ŌĒ	Q		15	23	, VIII	15	27	711	28	ns				
t <sub>dis</sub>	ŌĒ	Q		15	23	¥	15	27		28	ns				

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

						SN74L	_V373				
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC	= 5 V ± (	).5 V	VCC =	3.3 V ±	0.3 V	VCC =	2.7 V	UNIT
	( 51)	(6611 61)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX	
	D	_		8	16		11	22		28	
<sup>t</sup> pd	LE	Q		11	19		15	25		26	ns
t <sub>en</sub>	ŌĒ	Q		15	23		15	27		28	ns
<sup>t</sup> dis	ŌĒ	Q		15	23		15	27		28	ns

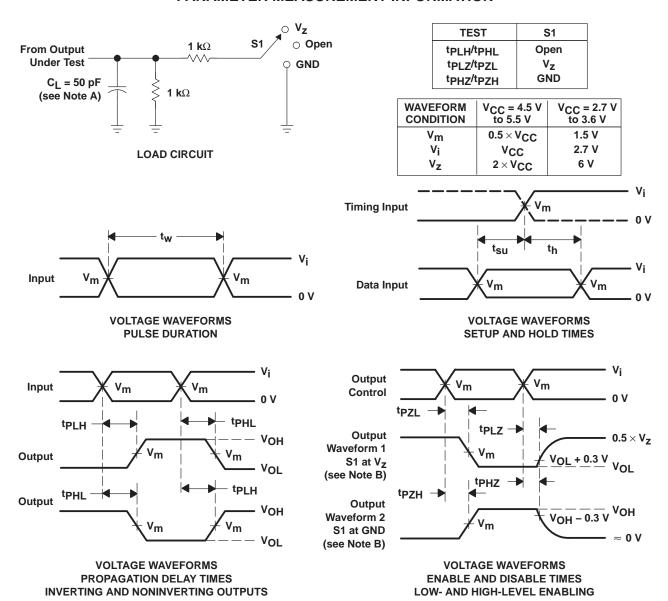
#### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	VCC	TYP	UNIT		
	Outputs enabled			3.3 V	47		
	Outputs disabled	0. 50.55	f 40 MH-		29		
Cpd	C <sub>pd</sub> Power dissipation capacitance per latch	Outputs enabled	$C_L = 50 \text{ pF},$	f = 10 MHz	5.7	112	pF
	Outputs disabled	1		5 V	62	]	

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ .
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







18-Sep-2008

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LV373DBLE	OBSOLETE	SSOP	DB	20	TBD	Call TI	Call TI
SN74LV373DW	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
SN74LV373DWR	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
SN74LV373PWLE	OBSOLETE	TSSOP	PW	20	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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